

TA2153FN

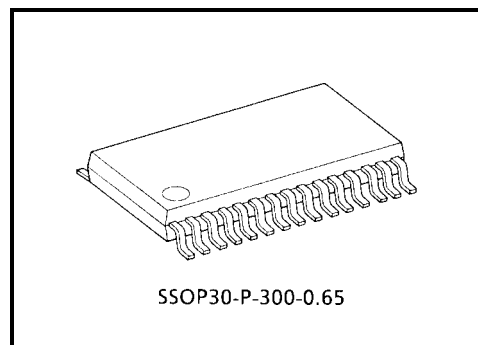
RF Amplifier for Digital Servo CD System

TA2153FN is a 3-beam type PUH compatible RF amplifier for digital servo to be used in the CD system.

In combination with a CMOS single chip processor TC9462F/TC9495F, a CD system can be composed very simply.

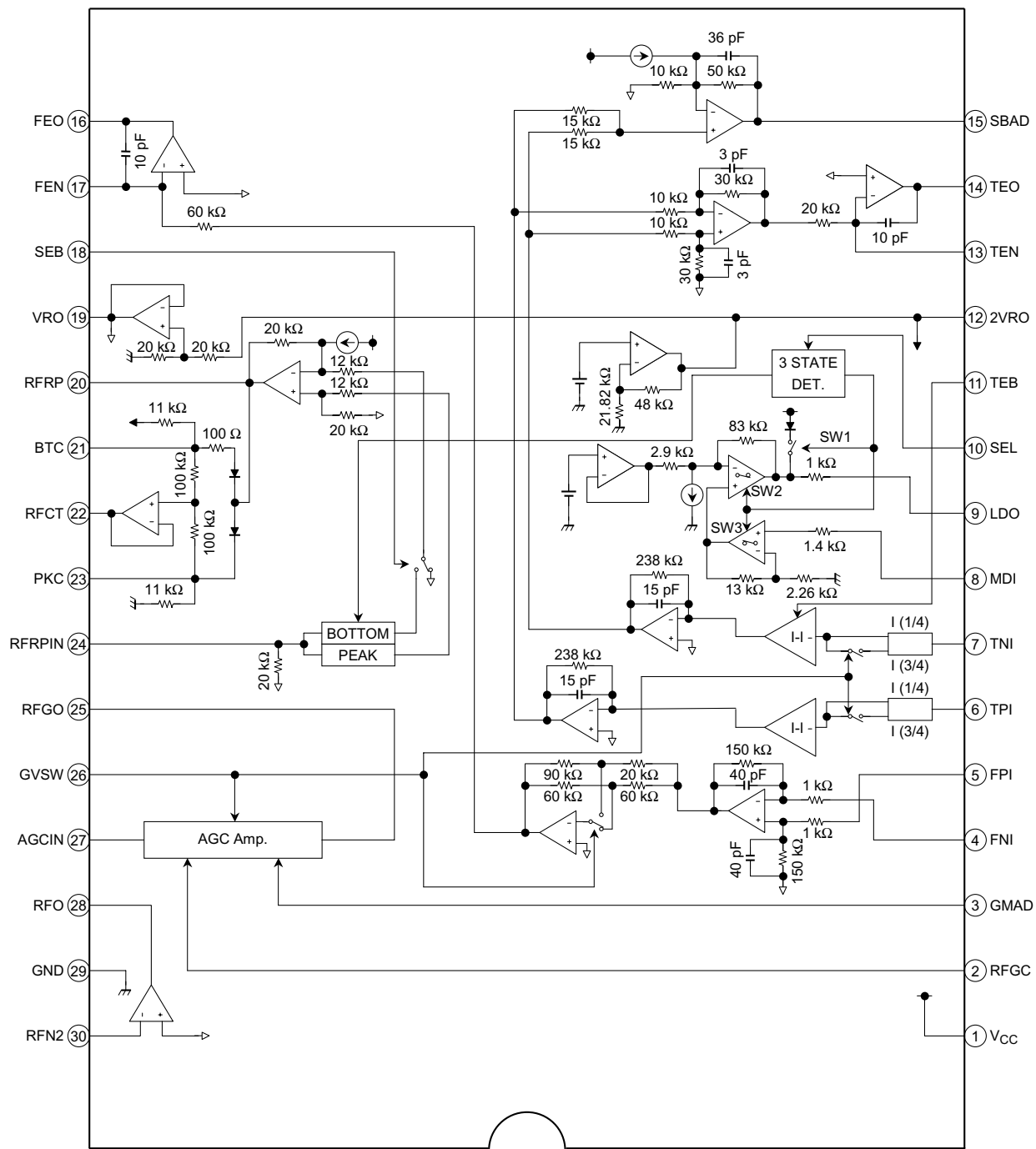
Features

- Built-in amplifier for reference (VRO, 2VRO) supply.
- Built-in auto laser power control circuit.
- Built-in RF amplifier.
- Built-in AGC amplifier.
- Built-in focus error amp and tracking error amp.
- Built-in sub-beam adder signal amplifier.
- Built-in gain change circuit for CD-RW.
- Capable of tracking balance control with TC9462F/TC9495F.
- Capable of RF gain adjustment circuit with TC9462F/TC9495F.
- Built-in signal amplifier for track counter.
- Capable of 4 times speed operation.
- 30 pin mini flat package.



Weight: 0.17 g (typ.)

Block Diagram



SEL	LDC			RFRP Detect Frequency
	SW1	SW2	SW3	
GND	ON	OFF	OFF	Low
HiZ	OFF	ON	ON	Low
VCC	OFF	ON	ON	High

GVSF	Mode
GND	CD-RW
HiZ	Normal
VCC	

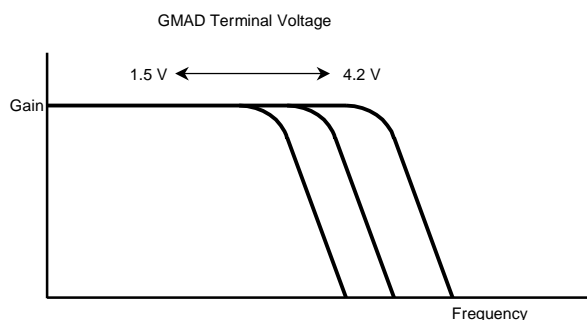
SEB	Bottom Detect	Peak Detect
GND	ON	ON
HiZ	ON	ON
VCC	OFF	ON

Pin Function

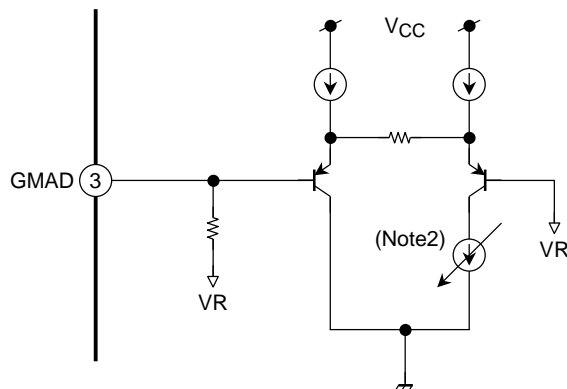
Pin No.	Symbol	I/O	Function Description	Remarks																
1	V _{CC}	—	Power supply input terminal.	—																
2	RFGC	I	RF amplitude adjustment control signal input terminal. Controlled by 3-PWM signals. (PWM carrier = 88.2 kHz)	3 signals input. (2VRO, VRO, GND)																
3	GMAD	I	Open loop gain adjustment terminal for AGC amp.	(Note1)																
4	FNI	I	Main beam I-V amp input terminal.	Connected to pin diode output B + D (through resistor).																
5	FPI	I	Main beam I-V amp input terminal.	Connected to pin diode output A + C (through resistor).																
6	TPI	I	Sub beam I-V amp input terminal.	Connected to pin diode output F.																
7	TNI	I	Sub beam I-V amp input terminal.	Connected to pin diode output E.																
8	MDI	I	Monitor photo diode amp input terminal.	Connected to monitor photo diode.																
9	LDO	O	Laser diode amp input terminal.	Connected to laser diode control circuit.																
10	SEL	I	Laser diode control signal input terminal and APC circuit ON/OFF control signal terminal. <table><tr><td>SEL Level</td><td>APC Circuit</td><td>LDO</td><td>Detect Frequency</td></tr><tr><td>GND</td><td>OFF</td><td>Connected to V_{CC} through resistor (1 kΩ)</td><td>Low</td></tr><tr><td>HiZ</td><td>ON</td><td>Control signal output</td><td>Low</td></tr><tr><td>V_{CC}</td><td>ON</td><td>Control signal output</td><td>High</td></tr></table>	SEL Level	APC Circuit	LDO	Detect Frequency	GND	OFF	Connected to V _{CC} through resistor (1 kΩ)	Low	HiZ	ON	Control signal output	Low	V _{CC}	ON	Control signal output	High	3 signals input. (V _{CC} , HiZ, GND)
SEL Level	APC Circuit	LDO	Detect Frequency																	
GND	OFF	Connected to V _{CC} through resistor (1 kΩ)	Low																	
HiZ	ON	Control signal output	Low																	
V _{CC}	ON	Control signal output	High																	
11	TEB	I	Tracking error balance adjustment signal input terminal. Controlled by 3-PWM signal. (PWM carrier = 88.2 kHz)	3 signals input. (2VRO, VRO, GND)																
12	2VRO	O	Reference voltage (2VRO) output terminal. 2VRO = 4.2 V when V _{CC} = 5 V	—																
13	TEN	I	TE amp negative input terminal.	Connected to TEO through feedback resistor.																
14	TEO	O	TE error signal output terminal.	—																
15	SBAD	O	Sub beam adder signal output terminal.	—																
16	FEO	O	Focus error signal output terminal.	—																
17	FEN	I	FE amp negative input terminal.	Connected to FEO through feedback resistor.																
18	SEB	I	RFRP output circuit switching terminal. <table><tr><td>SEB Level</td><td>Bottom Detection</td><td>Peak Detection</td></tr><tr><td>GND</td><td>ON</td><td>ON</td></tr><tr><td>V_{CC}</td><td>OFF</td><td>ON</td></tr></table>	SEB Level	Bottom Detection	Peak Detection	GND	ON	ON	V _{CC}	OFF	ON	Low (GND) is for normal use.							
SEB Level	Bottom Detection	Peak Detection																		
GND	ON	ON																		
V _{CC}	OFF	ON																		
19	VRO	O	Reference signal (VRO) output terminal. VRO = 2.1 V when V _{CC} = 5 V	—																
20	RFRP	O	Track count signal output terminal.	—																
21	BTC	I	Time constant adjustment terminal for bottom detection.	Adjusted by capacitance.																

Pin No.	Symbol	I/O	Function Description	Remarks								
22	RFCT	O	RFRP signal center level output terminal.	—								
23	PKC	I	Time constant adjustment terminal for peak detection.	Adjusted by capacitance.								
24	RFRPIN	I	Input terminal for track count signal output amp.	—								
25	RFGO	O	Output terminal for RF signal amplitude adjustment amp.	—								
26	GVSW	I	Amp (AGC, FE, TE) gain switching terminal. <div><table><tr><td>GVSW</td><td>Mode</td></tr><tr><td>GND</td><td>CD-RW</td></tr><tr><td>HiZ</td><td>Normal</td></tr><tr><td>V_{CC}</td><td>Normal</td></tr></table></div>	GVSW	Mode	GND	CD-RW	HiZ	Normal	V _{CC}	Normal	Low (GND) is for 5 times gain.
GVSW	Mode											
GND	CD-RW											
HiZ	Normal											
V _{CC}	Normal											
27	AGCIN	I	Input terminal for RF signal amplitude adjustment amp.	Connected to RFO through capacitance.								
28	RFO	O	Output terminal for RF signal amp.	—								
29	GND	—	Ground terminal.	—								
30	RFN2	I	Input terminal for RF signal amp.	Connected to pin-diode output A + B + C + D (through resistor).								

Note 1: Pin3 (GMAD) is gm adjustment terminal for AGC amp by applying a voltage (between 1.5 V and 4.2 V).
If pin3 (GMAD) is open, voltage of this terminal is fixed VR by IC interior.
Characteristic of frequency (open-loop characteristic) and voltage is as below.



By changing a voltage (pin3) between 1.5 V and 4.2 V, frequency band width is changed.



Note 2: Current is changed by pin3 (GMAD) voltage.

Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Power supply voltage	V _{CC}	8	V
Power dissipation	P _D	500	mW
Operating temperature	T _{opr}	−40~85	°C
Storage temperature	T _{stg}	−55~150	°C

Electrical Characteristics (unless otherwise specified, $V_{CC} = 5\text{ V}$, $T_a = 25^\circ\text{C}$)

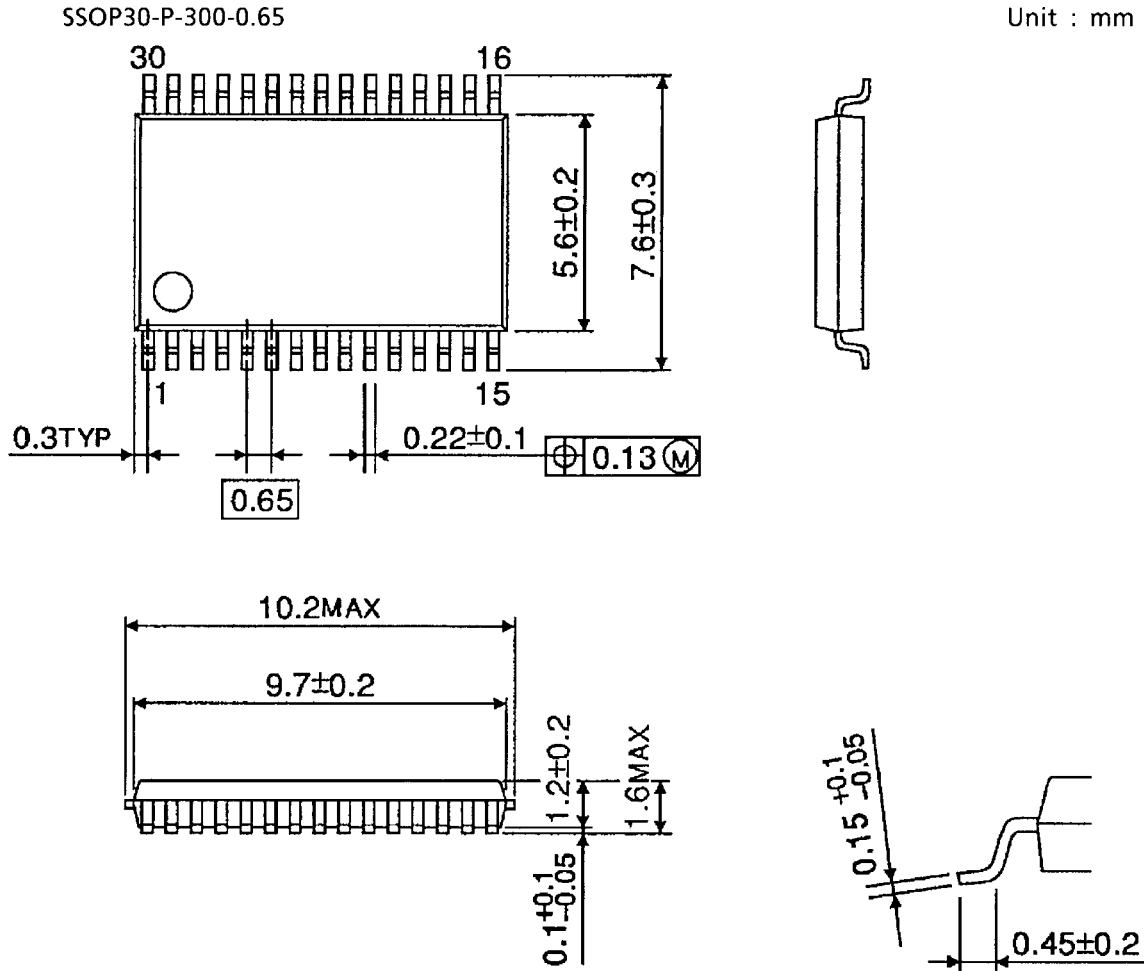
Characteristics		Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit
Power supply	Assured power supply voltage	V_{CC}	—	—	4.5	5.0	5.5	V
	Power supply current	I_{CC}	—	SEL = HiZ	26	35	44	mA
Reference voltage (2VRO)	Reference voltage	2VR	—	—	4.0	4.2	4.4	V
	Output current	I_{OH2}	—	$\Delta V = -0.2\text{ V}$	2.0	—	—	mA
	Input current	I_{OL2}	—	$\Delta V = +0.1\text{ V}$	0.1	—	—	
Reference voltage (VRO)	Reference voltage	VR	—	—	2.0	2.1	2.2	V
	Reference voltage limit	ΔVR	—	$2 \times VR/2VR - 1$	-3.0	0	3.0	%
	Output current	I_{OH1}	—	$\Delta V = -0.2\text{ V}$	5.0	—	—	mA
	Input current	I_{OL1}	—	$\Delta V = +0.1\text{ V}$	5.0	—	—	
RF1	Frequency band width	fc	—	-3dB point, $R_{IN} = 6\text{ k}\Omega$ Between RFO – RFN2: 33 k Ω	—	8	—	MHz
	Output slew rate	SR	—	$C_{RFO} = 20\text{ pF}$, $R_{IN} = 6\text{ k}\Omega$ Between RFO – RFN2: 33 k Ω	—	22	—	V/ μs
	Output offset voltage	V_{OS}	—	VR Reference Between RFO – RFN2: 33 k Ω Input: VR short	—	-100	—	mV
	Upper limit output voltage	V_{OH}	—	GND Reference	3.8	—	—	V
	Lower limit output voltage	V_{OL}	—	GND Reference	—	—	0.9	
	Permissive load resistance	R_{LM}	—	—	10	—	—	k Ω
RF2 (AGC)	Lower limit voltage gain 1 (normal mode)	Gv1L	—	$f = 1\text{ MHz}$, RFGC = 0.6 V, GVSW = V_{CC} , GMAD = VR	0.6	0.7	0.8	V/V
	Upper limit voltage gain 1 (normal mode)	Gv1H	—	$f = 1\text{ MHz}$, RFGC = 3.6 V, GVSW = V_{CC} , GMAD = VR	1.3	1.5	1.7	
	Lower limit voltage gain 2 (CD-RW mode)	Gv2L	—	$f = 1\text{ MHz}$, RFGC = 0.6 V, GVSW = GND, GMAD = VR	2.7	3.2	3.6	
	Upper limit voltage gain 2 (CD-RW mode)	Gv2H	—	$f = 1\text{ MHz}$, RFGC = 3.6 V, GVSW = GND, GMAD = VR	5.8	6.8	7.7	
	Frequency band width (normal mode)	fc1	—	-0.5dB point, RFGC = 2.1 V, GVSW = V_{CC} , GMAD = VR	—	12	—	MHz
	Frequency band width (CD-RW mode)	fc2	—	-0.5dB point, RFGC = 2.1 V, GVSW = GND, GMAD = VR	—	12	—	
	Output slew rate	SR	—	$C_{RFGO} = 20\text{ pF}$	—	40	—	V/ μs
	Output offset voltage 1 (normal mode)	V_{OS1}	—	VR Reference GMAD = VR Input: Open	GVSW = V_{CC}	—	-100	mV
	Output offset voltage 2 (CD-RW mode)	V_{OS2}	—		GVSW = GND	—	0	
	Upper limit output voltage	V_{OH}	—	GND Reference	3.7	—	—	V
	Lower limit output voltage	V_{OL}	—	GND Reference	—	—	0.9	
	Permissive load resistance	R_{LM}	—	—	10	—	—	k Ω
APC	Voltage gain	Gv	—	$f = 1\text{ kHz}$	—	200	—	V/V
	Operation ref. Voltage	V_{MDI}	—	$V_{LDO} = 3.5\text{ V}_{DC}$	170	178	192	mV
	LD off voltage	V_{LDOP}	—	SEL = GND, V_{CC} Reference	-0.7	—	—	V
	Input bias current	I_I	—	MDI = 178 mV	-200	—	200	nA

Characteristics		Symbol	Test Circuit	Test Condition		Min	Typ.	Max	Unit
FE	Voltage gain 1 (normal mode)	Gv1	—	$f = 1 \text{ kHz}$ $R_{NF} = 91 \text{ k}\Omega$ $R_{FI} = 47 \text{ k}\Omega$	GVSW = V _{CC}	4.3	4.8	5.3	V/V
	Voltage gain 2 (CD-RW mode)	Gv2	—		GVSW = GND	19.3	21.6	23.9	
	Gain balance 1 (normal mode)	GB1	—	$f = 1 \text{ kHz}$ $R_{NF} = 91 \text{ k}\Omega$ $R_{FI} = 47 \text{ k}\Omega$	GVSW = V _{CC}	-1.0	—	1.0	dB
	Gain balance 2 (CD-RW mode)	GB2	—		GVSW = GND	-1.0	—	1.0	
	Frequency band width	fc	—	-3dB point		—	26.5	—	kHz
	Output offset voltage 1 (normal mode)	V _{OS1}	—	$R_{NF} = 91 \text{ k}\Omega$ $R_{FI} = 47 \text{ k}\Omega$ VR Reference Input: VR short	GVSW = V _{CC}	-20	—	20	mV
	Output offset voltage 2 (CD-RW mode)	V _{OS2}	—		GVSW = GND	-50	—	50	
	Upper limit output voltage	V _{OH}	—	GND Reference		3.8	—	—	V
	Lower limit output voltage	V _{OL}	—	GND Reference		—	—	0.5	
	Permissive load resistance	R _{LM}	—	—		10	—	—	k Ω
TE	Voltage gain 1 (normal mode)	Gv1	—	$f = 1 \text{ kHz}$ $R_{FN} = 100 \text{ k}\Omega$ $R_{TI} = 47 \text{ k}\Omega$	GVSW = V _{CC}	10.9	12.3	13.5	V/V
	Voltage gain 2 (CD-RW mode)	Gv2	—		GVSW = GND	50	56	60	
	Voltage gain adjustable range	ΔGv	—	T_{NI} input TEB = VR Reference	TEB = GND	40	45	50	%
					TEB = 2VR	-50	-45	-40	
	Gain balance 1 (normal mode)	GB1	—	$f = 1 \text{ kHz}$ $R_{NF} = 100 \text{ k}\Omega$ $R_{FI} = 47 \text{ k}\Omega$ TEB = VR	GVSW = V _{CC}	-1.0	—	1.0	dB
	Gain balance 2 (CD-RW mode)	GB2	—		GVSW = GND	-1.0	—	1.0	
	Frequency characteristic cut-off frequency	fc	—	$R_{NF} = 100 \text{ k}\Omega$ -3dB point		—	44	—	kHz
	Output offset voltage (normal mode)	V _{OS1}	—	$R_{NF} = 100 \text{ k}\Omega$ $R_{FI} = 47 \text{ k}\Omega$ VR Reference Input: VR short	GVSW = V _{CC}	-80	—	80	mV
	Output offset voltage (CD-RW mode)	V _{OS2}	—		GVSW = GND	-300	—	300	
	Upper limit output voltage	V _{OH}	—	GND Reference		3.8	—	—	V
	Lower limit output voltage	V _{OL}	—	GND Reference		—	—	0.5	
	Permissive load resistance	R _{LM}	—	—		10	—	—	k Ω
SBAD	Voltage gain 1 (normal mode)	Gv1	—	$f = 1 \text{ kHz}$ $R_{TI} = 47 \text{ k}\Omega$ TEB = VR	GVSW = V _{CC}	2.0	2.7	3.4	V/V
	Voltage Gain 2 (CD-RW mode)	Gv2	—		GVSW = GND	9.0	12.2	15.3	
	Frequency Band Width	fc	—	-3dB point		—	44	—	kHz
	Operation reference voltage 1 (normal mode)	V _{OPR1}	—	VR Reference $R_{TI} = 47 \text{ k}\Omega$ Input: VR short	GVSW = V _{CC}	-1.15	-1.05	-0.95	V
	Operation reference voltage 2 (CD-RW mode)	V _{OPR2}	—		GVSW = GND	-1.0	-0.9	-0.8	
	Upper limit output voltage	V _{OH}	—	GND Reference		3.8	—	—	V
	Lower limit output voltage	V _{OL}	—	GND Reference		—	—	1.3	
	Permissive load resistance	R _{LM}	—	—		10	—	—	k Ω

Characteristics		Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit
RFRP	Voltage gain	Gv	—	—	—	1.7	—	V/V
	Detection frequency characteristic 1	fc1	—	SEL = HiZ	—	100	—	kHz
	Detection frequency characteristic 2	fc2	—	SEL = V _{CC}	—	200	—	
	Operation reference voltage 1	V _{OPR1}	—	VR Reference No Input	−1.1	−1.0	−0.9	V
	Operation reference voltage 2	V _{OPR2}	—	VR Reference 700 kHz, 1.2 V _{p-p}	0.7	0.8	0.9	
	Permissive load resistance	R _{LM}	—	—	10	—	—	kΩ
RFCT	Detection frequency characteristic 1	fc1	—	C _{BTC} = 0.22 μF	—	70	—	Hz
RFRP → RFCT	Detection frequency characteristic 2	fc2	—	C _{PKC} = 0.22 μF	—	70	—	
	Output offset voltage	V _{OS}	—	RFRP Reference, RFCT	−50	—	50	mV

Note: If the IC is used abnormally (ex. wrongly mounted), it may be damaged or destroyed.

Package Dimensions



Weight: 0.17 g (typ.)

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